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Measurement of UKRI-MPWO after irradiation: An HV-CMOS prototype for high radiation tolerance

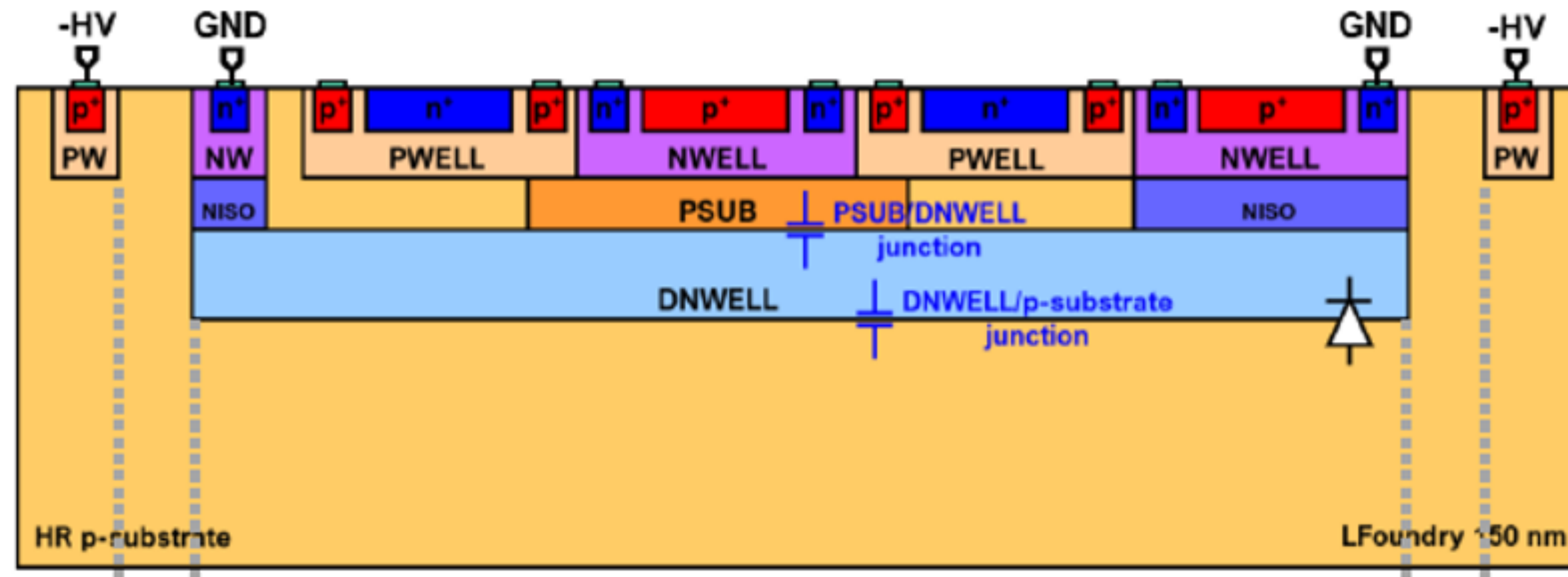
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- Sensing diode and readout electronics are in the same substrate (monolithic).
- High bias voltage forms a wide depletion region (radiation tolerant).
- Single layer structure → low cost, low material budget.
- Both NMOS and PMOS transistors can be implemented (full CMOS).



Cross-section of a typical large fill-factor HV-CMOS sensor

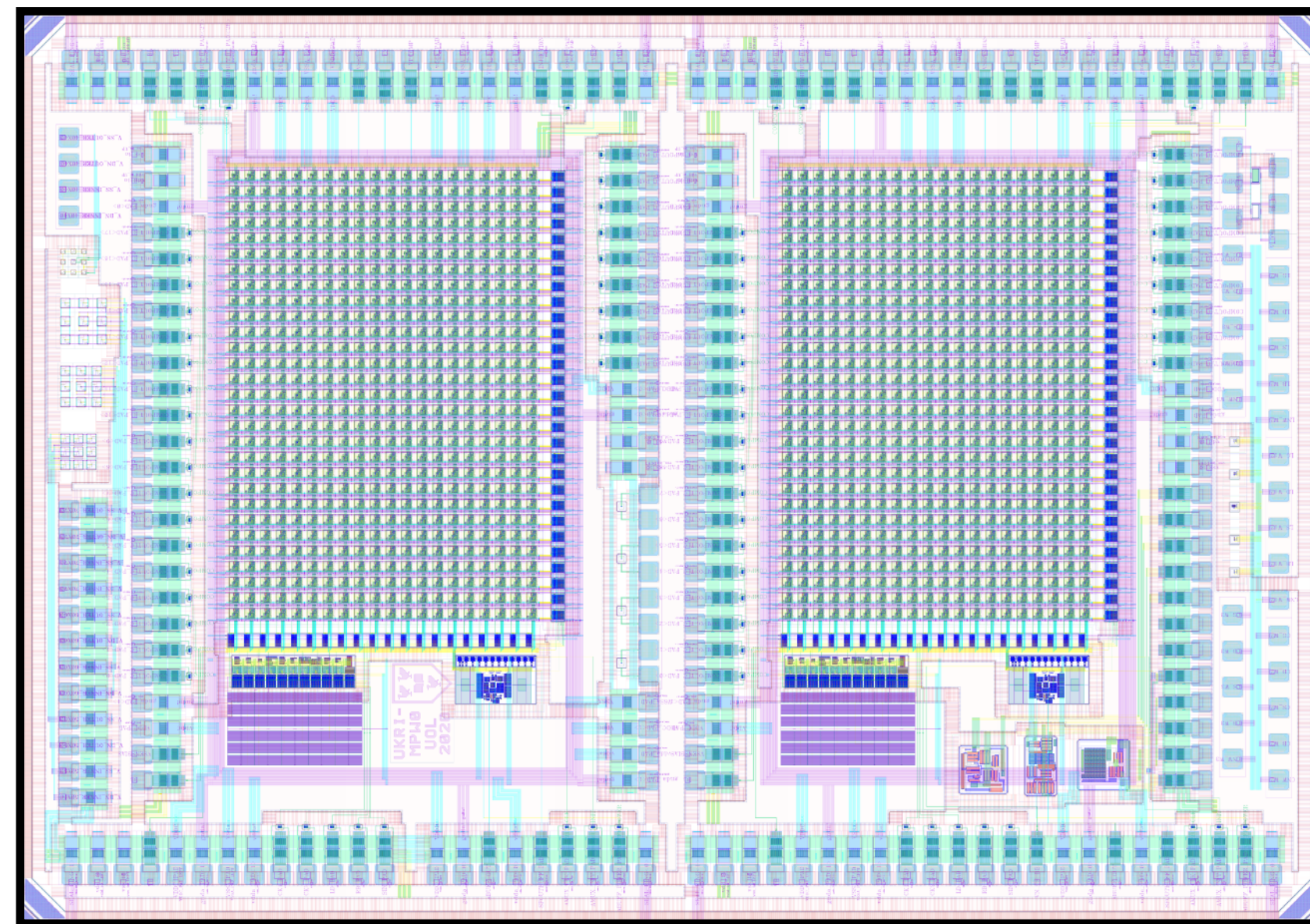
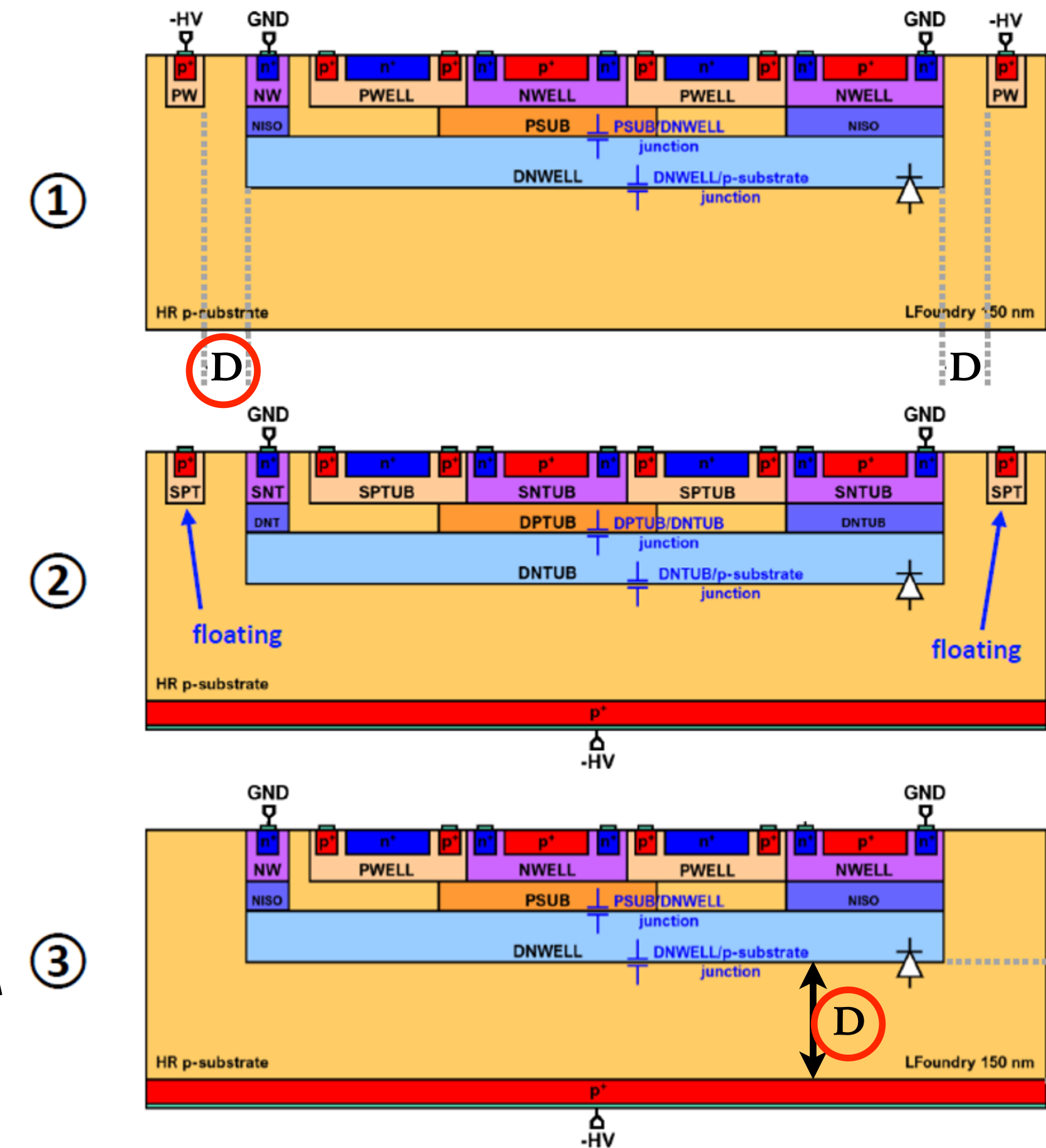
- Much higher luminosity ($> 5 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$) in future experiments.
- To survive radiation damage after long operation, pixel trackers must have higher radiation tolerance.
- The table below compares the best achieved HV-CMOS performance with the tracking detector requirements for future experiments.

| | HV-CMOS performance | HL-LHC | FCC-hh |
|--|--|--|--|
| Radiation tolerance | $2 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$ | $10^{16} \text{ n}_{\text{eq}}/\text{cm}^2/\text{y}$ | $10^{16} - 10^{17} \text{ n}_{\text{eq}}/\text{cm}^2/\text{y}$ |
| Pixel size | $50 \times 50 \mu\text{m}^2$ | $50 \times 50 \mu\text{m}^2$ | $25 \times 50 \mu\text{m}^2$ |
| Time resolution | 3.7 ns | 0.2* - 1000 ns** | $\sim 100 \text{ ps}$ |
| Thickness (material budget) | $50 \mu\text{m}$ | 0.1%** - 2% X_0/layer | 1% X_0/layer |

*LHCb requirement; **ALICE requirement

UKRI-MPW0: new cross-section

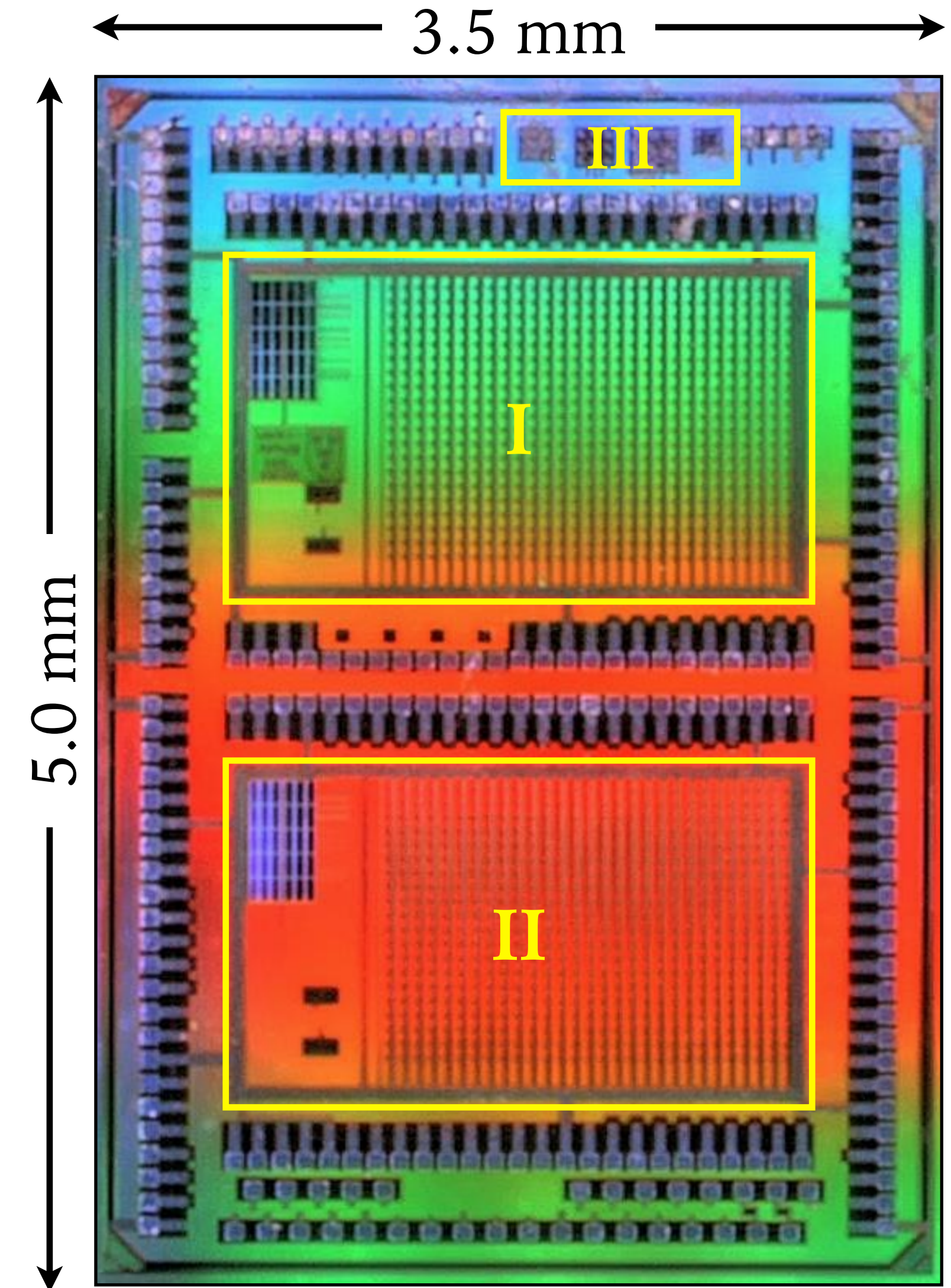
- 3 different schemes for high voltage biasing:
 - HV biased from the topside only (commonly used);
 - HV biased from the backside with floating topside contacts (has been tested);
 - HV biased from the backside, no topside contacts (first use in UKRI-MPW0).



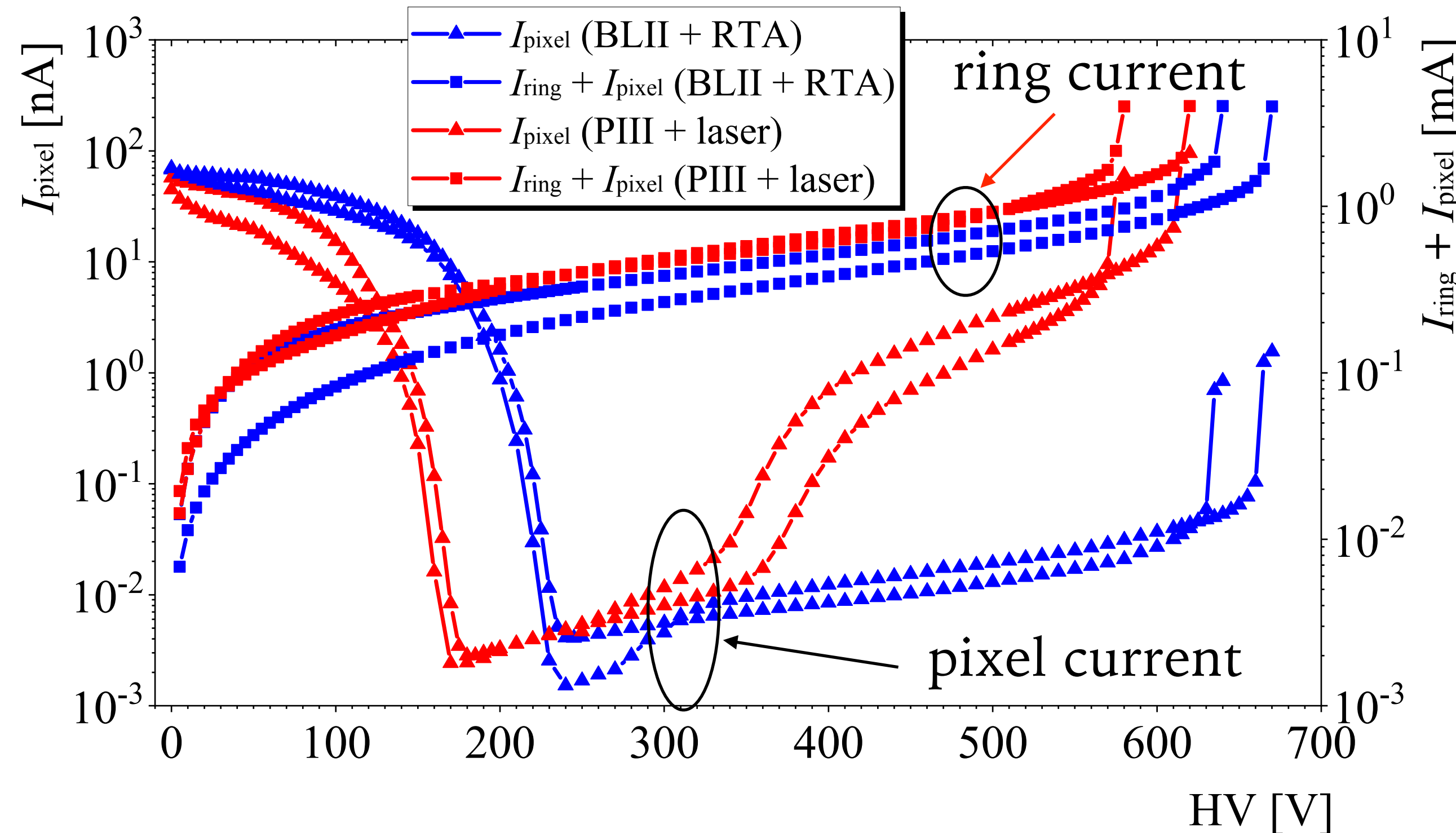
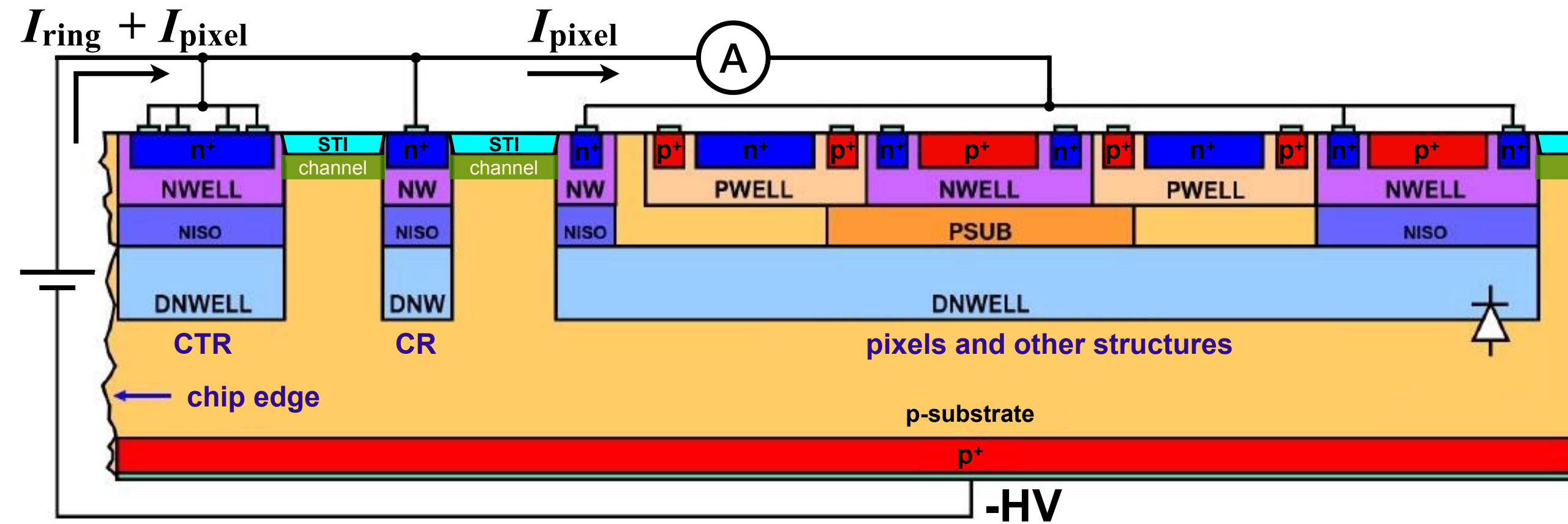
UKRI-MPW0

- Depletion depth $d \propto \sqrt{\rho \cdot V_{bias}}$.
- High V_{bias} maintains a wide depletion region after radiation \rightarrow better radiation tolerance.

- I. A 20×29 pixel matrix with 3 pixel flavours (using traditional linear transistors);
- II. Pixel matrix with 2 Enclosed Layout Transistors (ELT) inside each pixel for TID tolerance;
- III. Test structures for I-V and Edge-TCT.
 - LFoundry LF15A process (150 nm).
 - Two wafers with high resistivity of $1.9 \text{ k}\Omega\cdot\text{cm}$.
 - Thinned to $280 \mu\text{m}$ using TAIKO grinding.
 - Wafer 1: p^+ on the backside was implanted using beamline and activated with **Rapid Thermal Annealing (RTA)**.
 - Wafer 2: p^+ was implanted by **plasma** and activated with **laser annealing**.



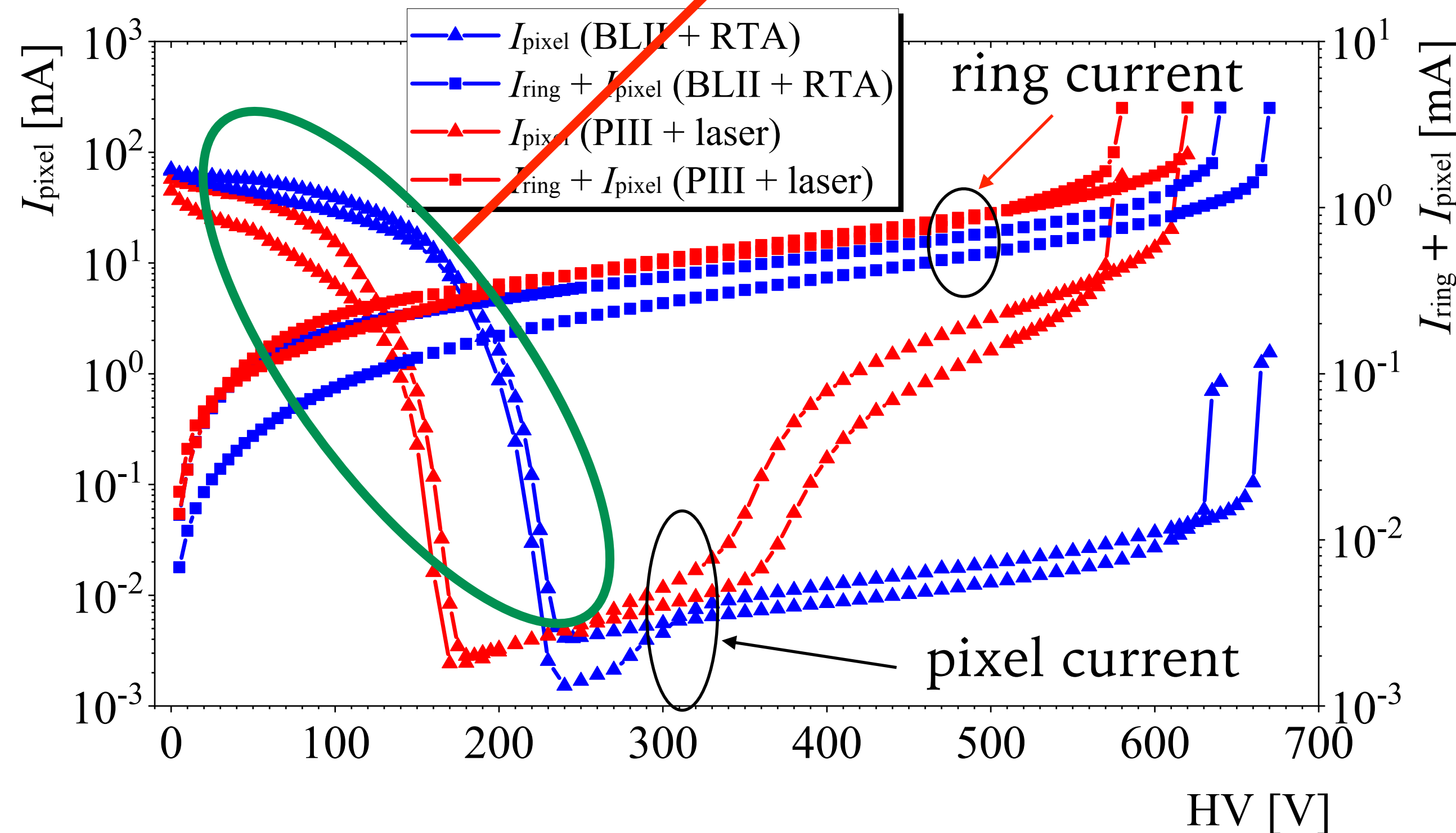
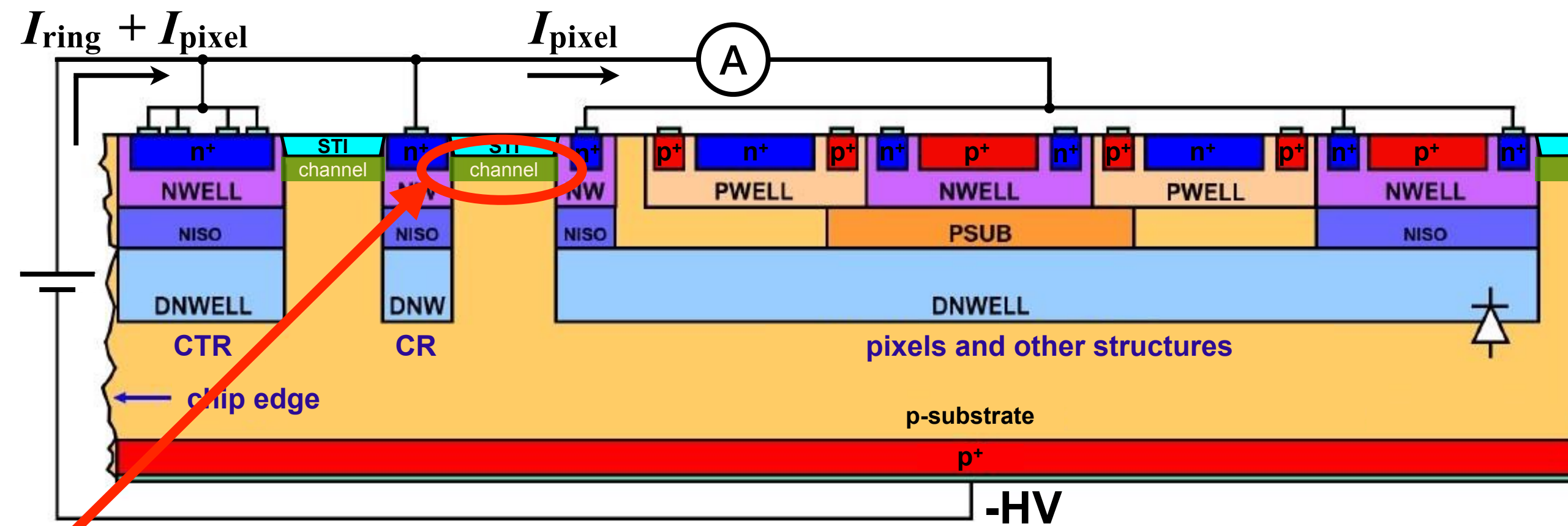
- N-type rings:
 - Current Terminating Ring (CTR)
 - Clean-up Ring (CR)



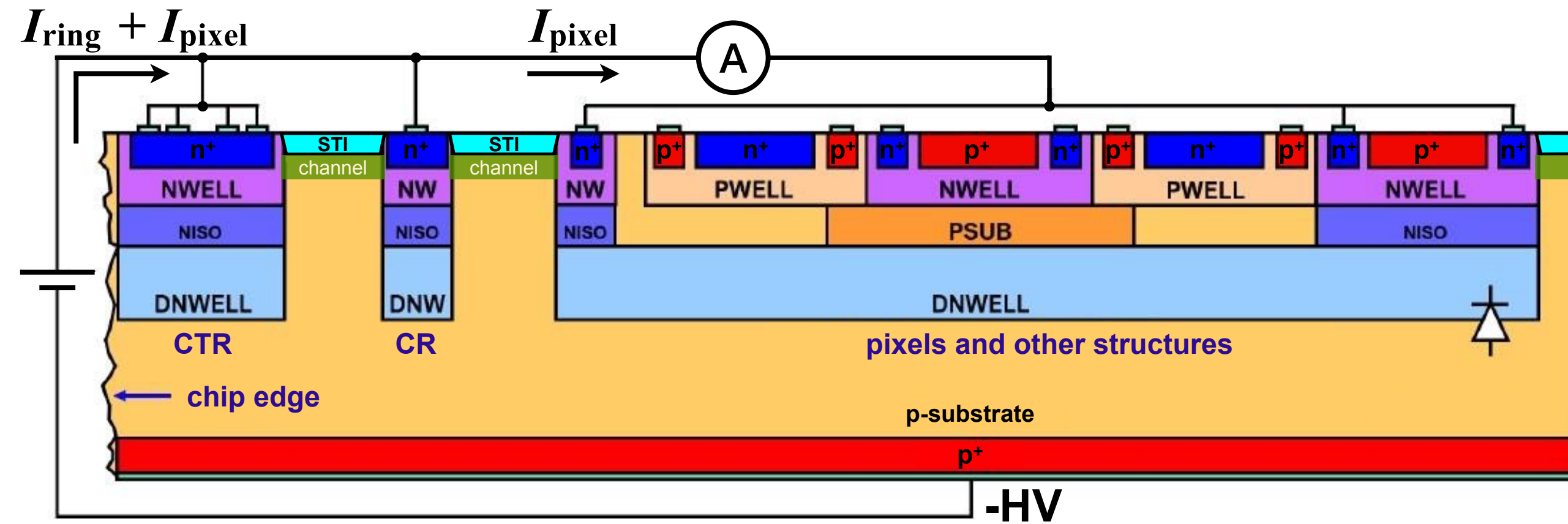
un-irradiated

- Reach 4 mA compliance at > 600 V (thermal runaway, not real breakdown).

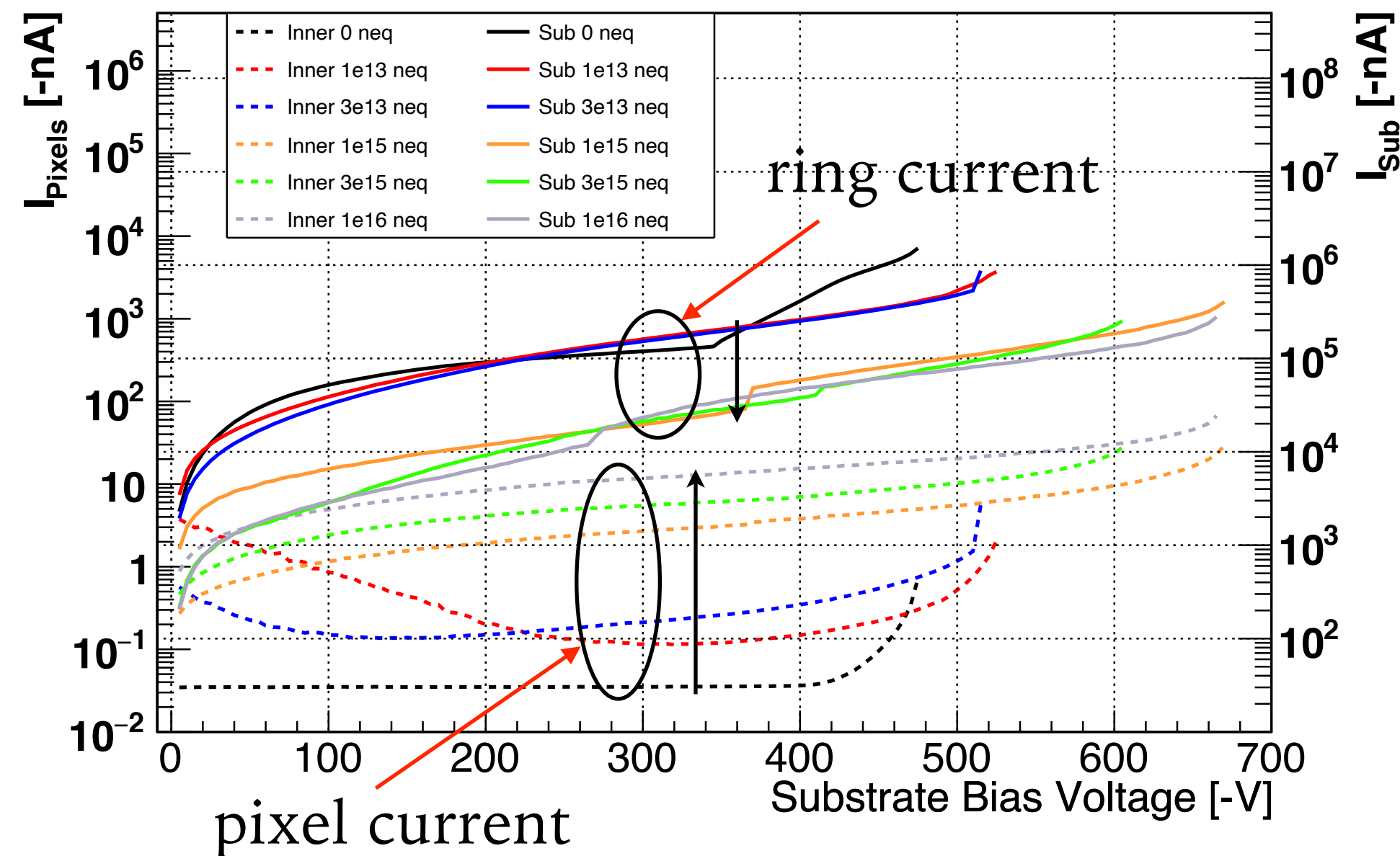
- High pixel current at low bias, caused by a parasitic channel under STI.
- Channel is closed by high bias voltage.



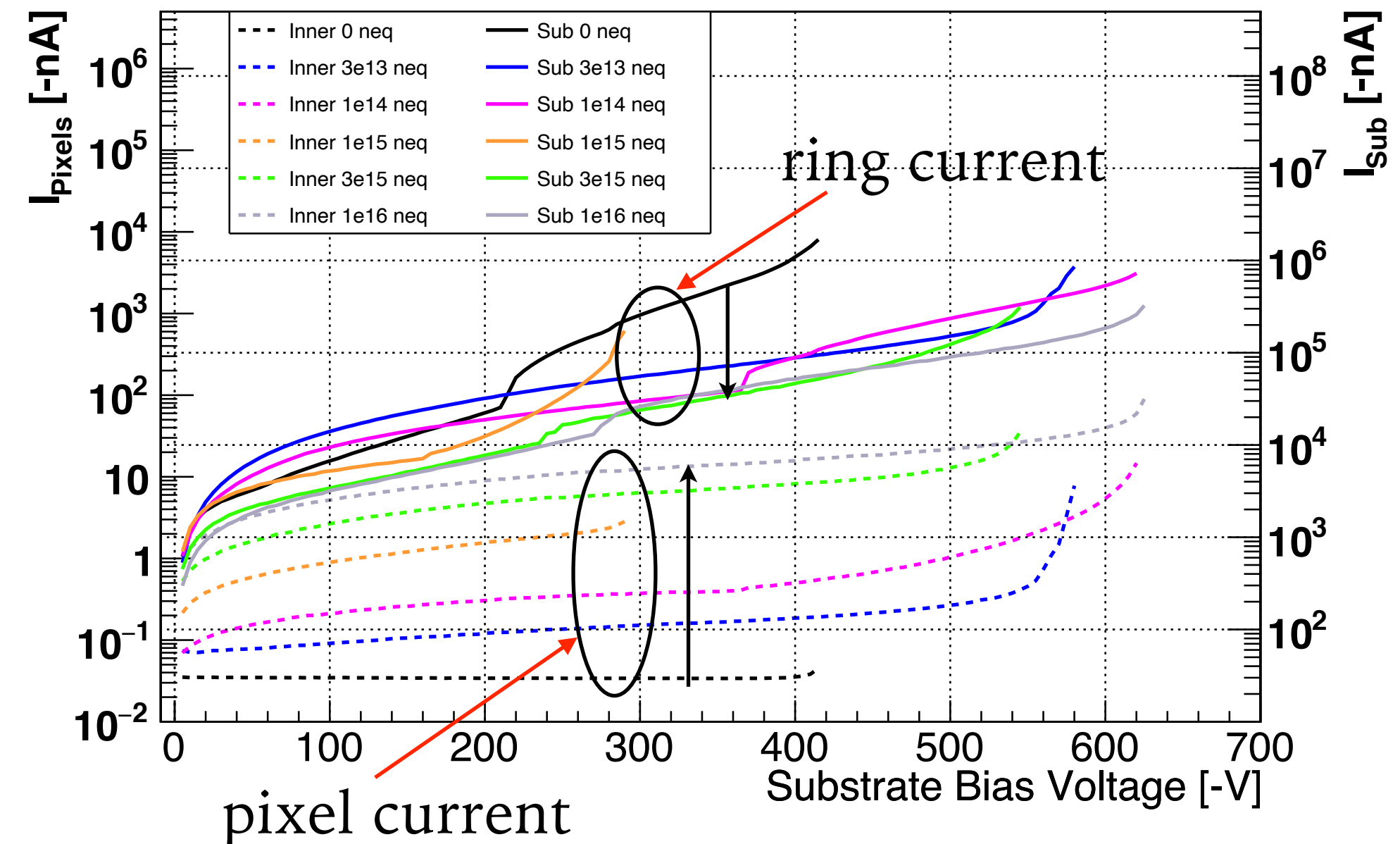
- N-type rings:
 - Current Terminating Ring (CTR)
 - Clean-up Ring (CR)
- Higher fluence \rightarrow higher pixel leakage current and lower ring leakage current.
- Reach compliance at larger bias voltage.



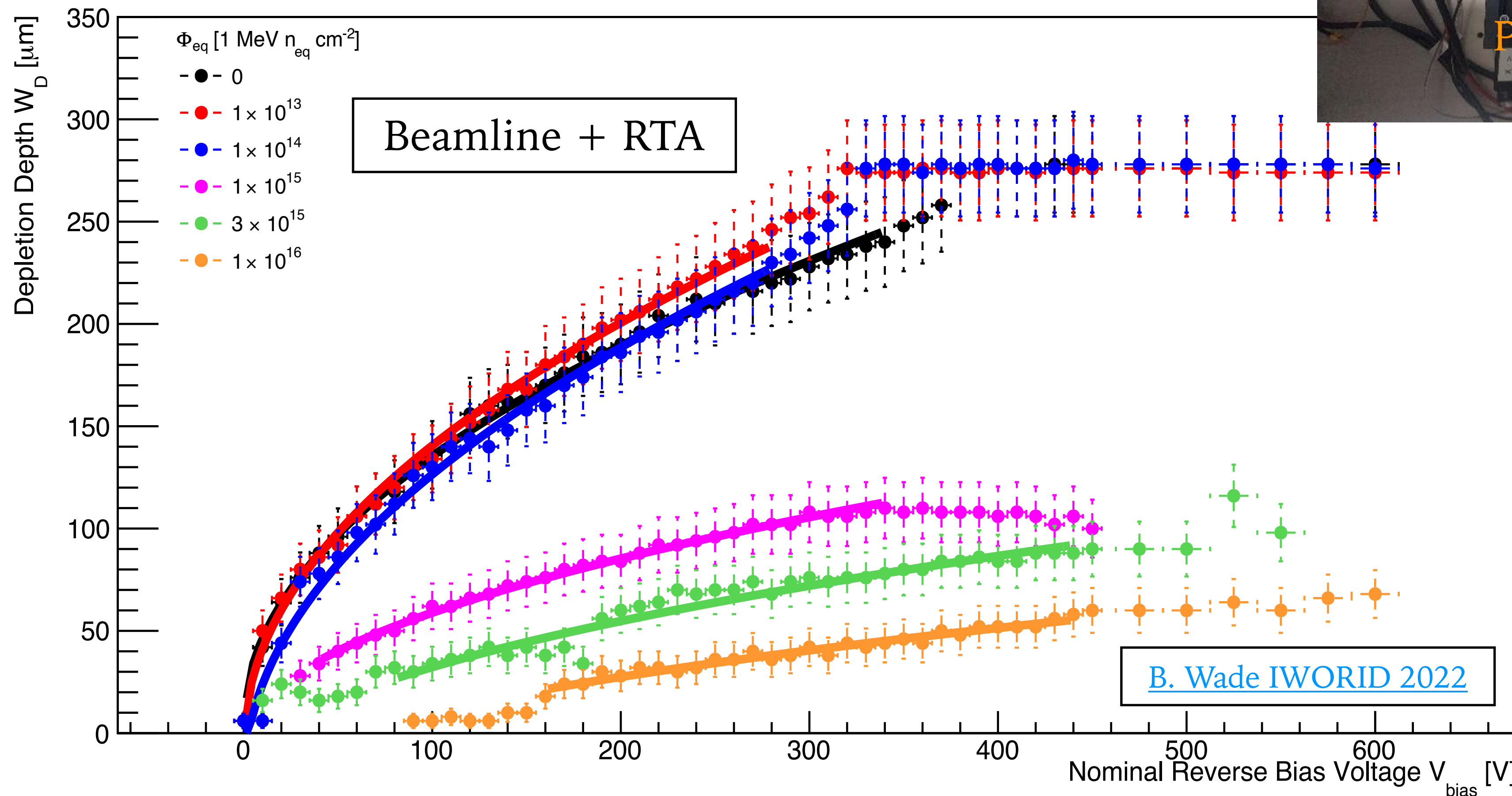
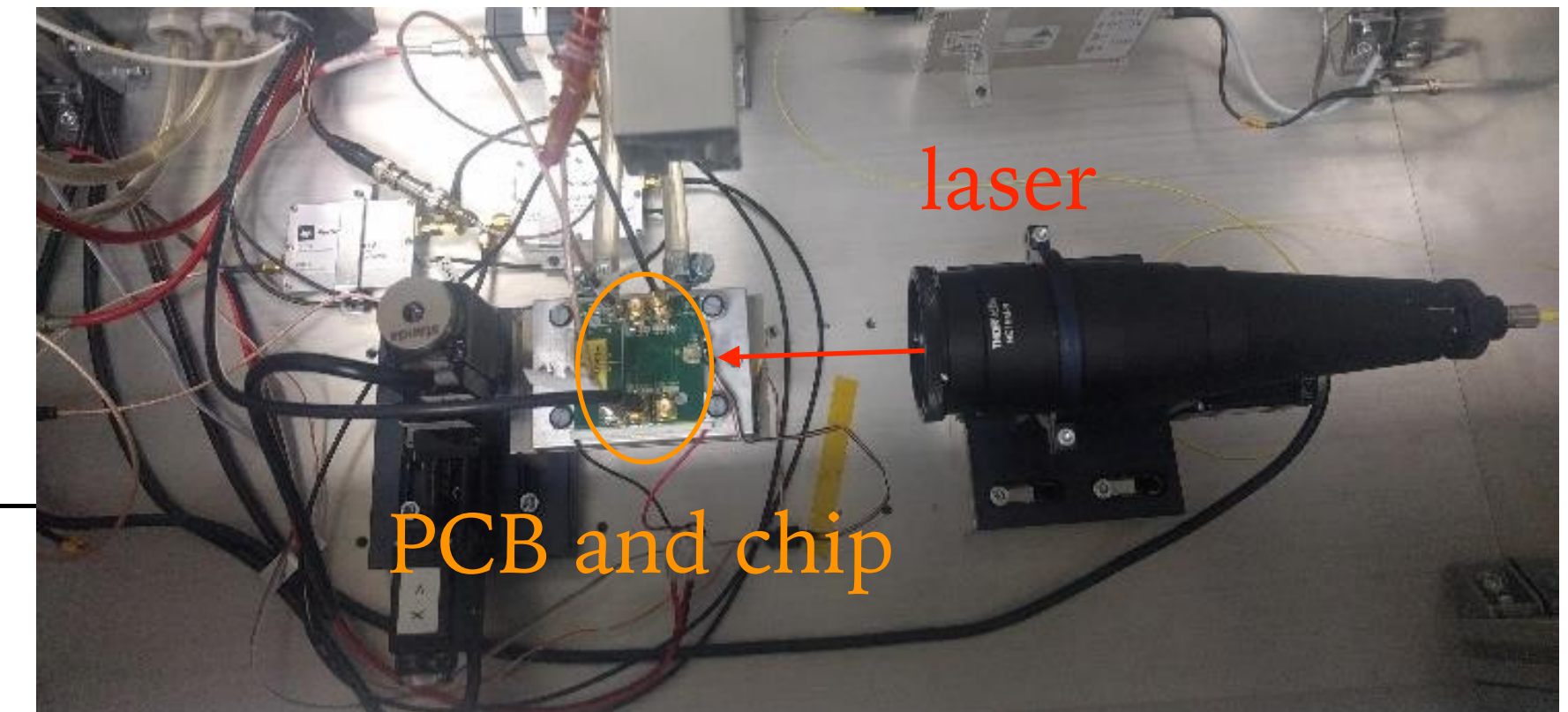
Plasma + laser annealing



Beamline + RTA

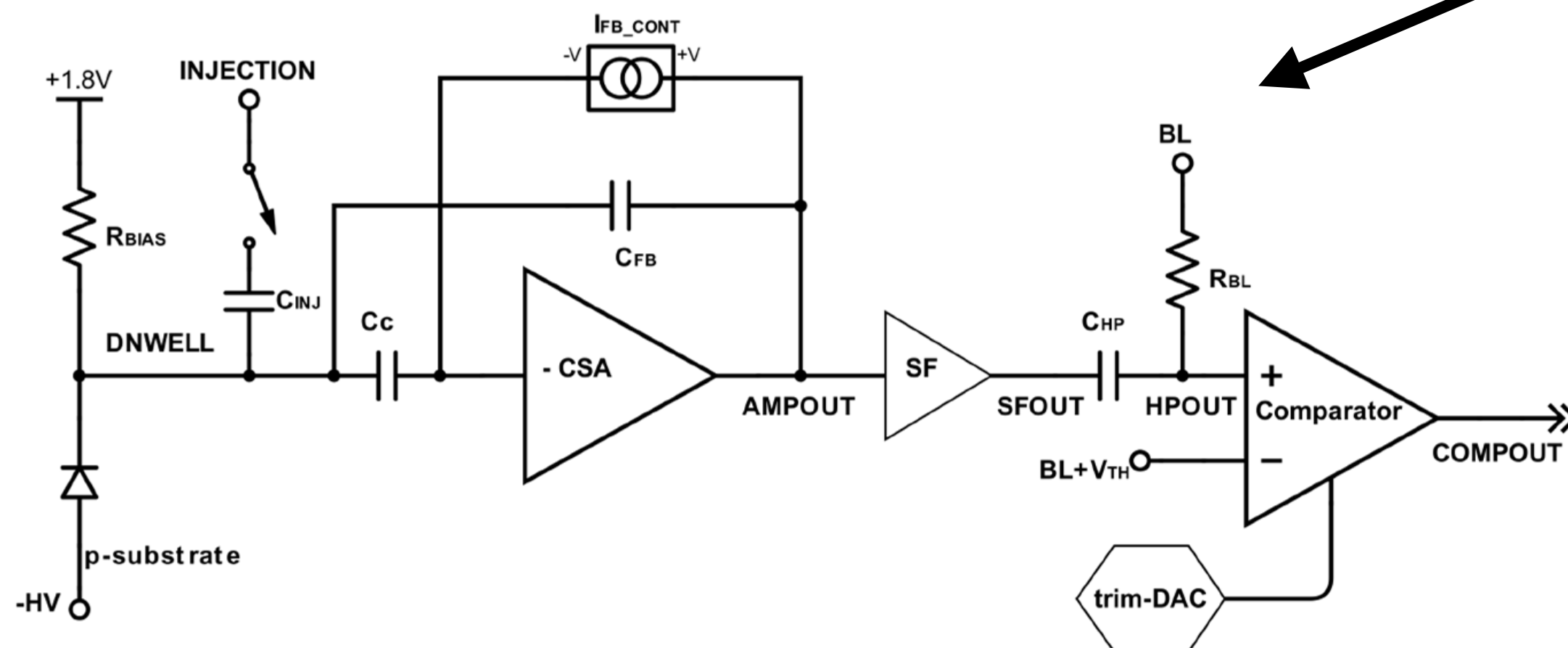
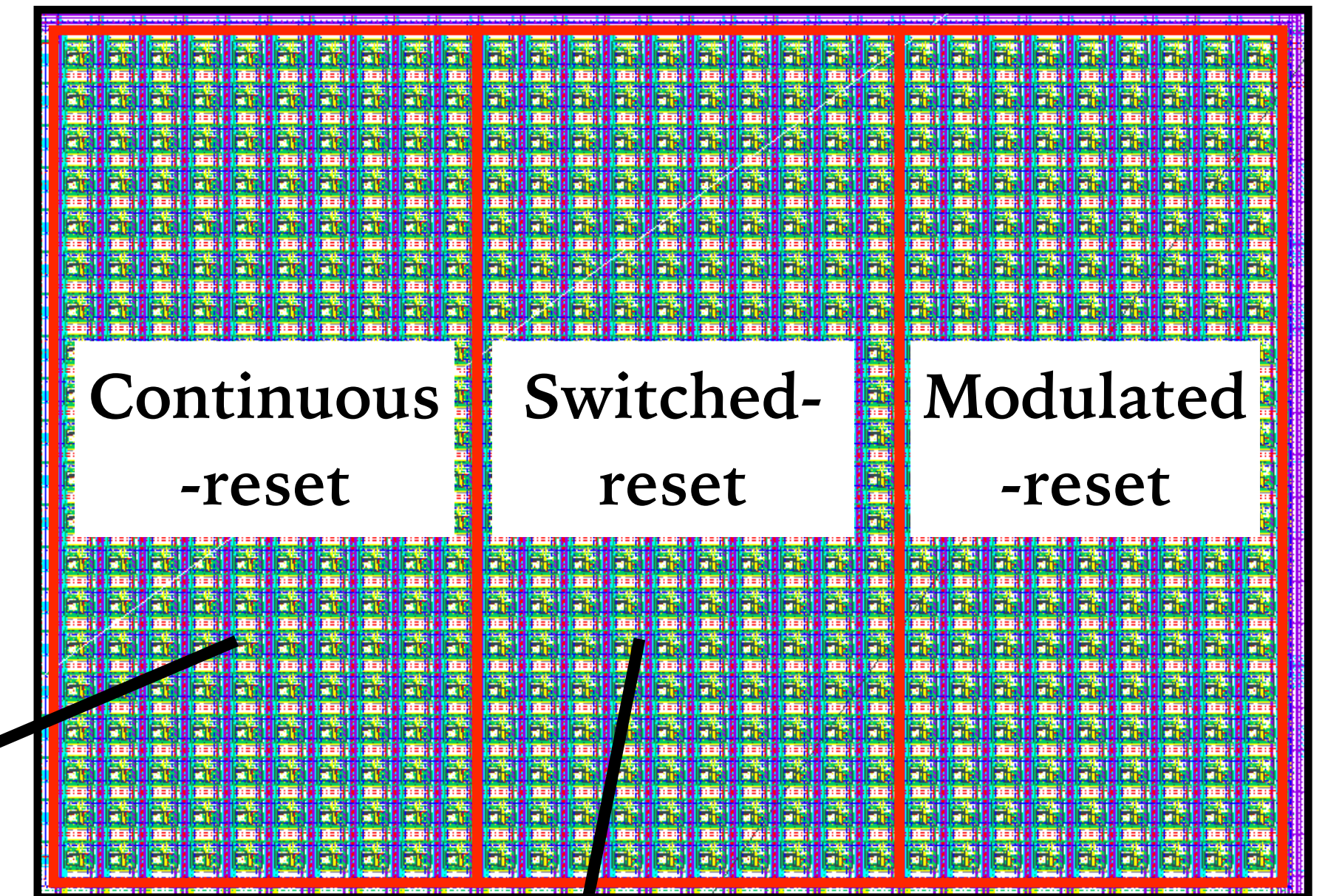


- Edge-TCT to measure depletion depth at different bias and fluence.

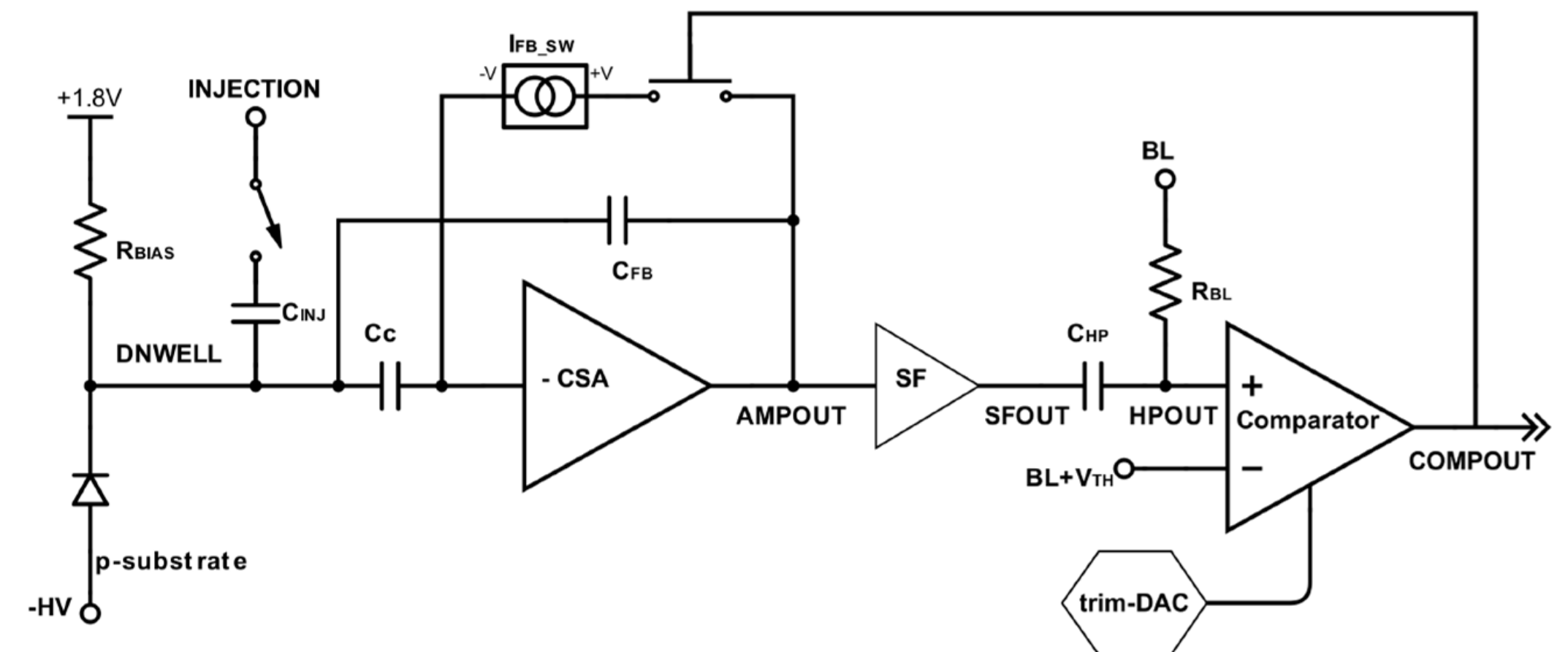


- Chip is fully depleted at 300 V for $1 \times 10^{14} \text{ n}_{eq}/\text{cm}^2$ (chip thickness: $280 \mu\text{m}$).
- Depletion depth $> 50 \mu\text{m}$ is achieved with $1 \times 10^{16} \text{ n}_{eq}/\text{cm}^2$.

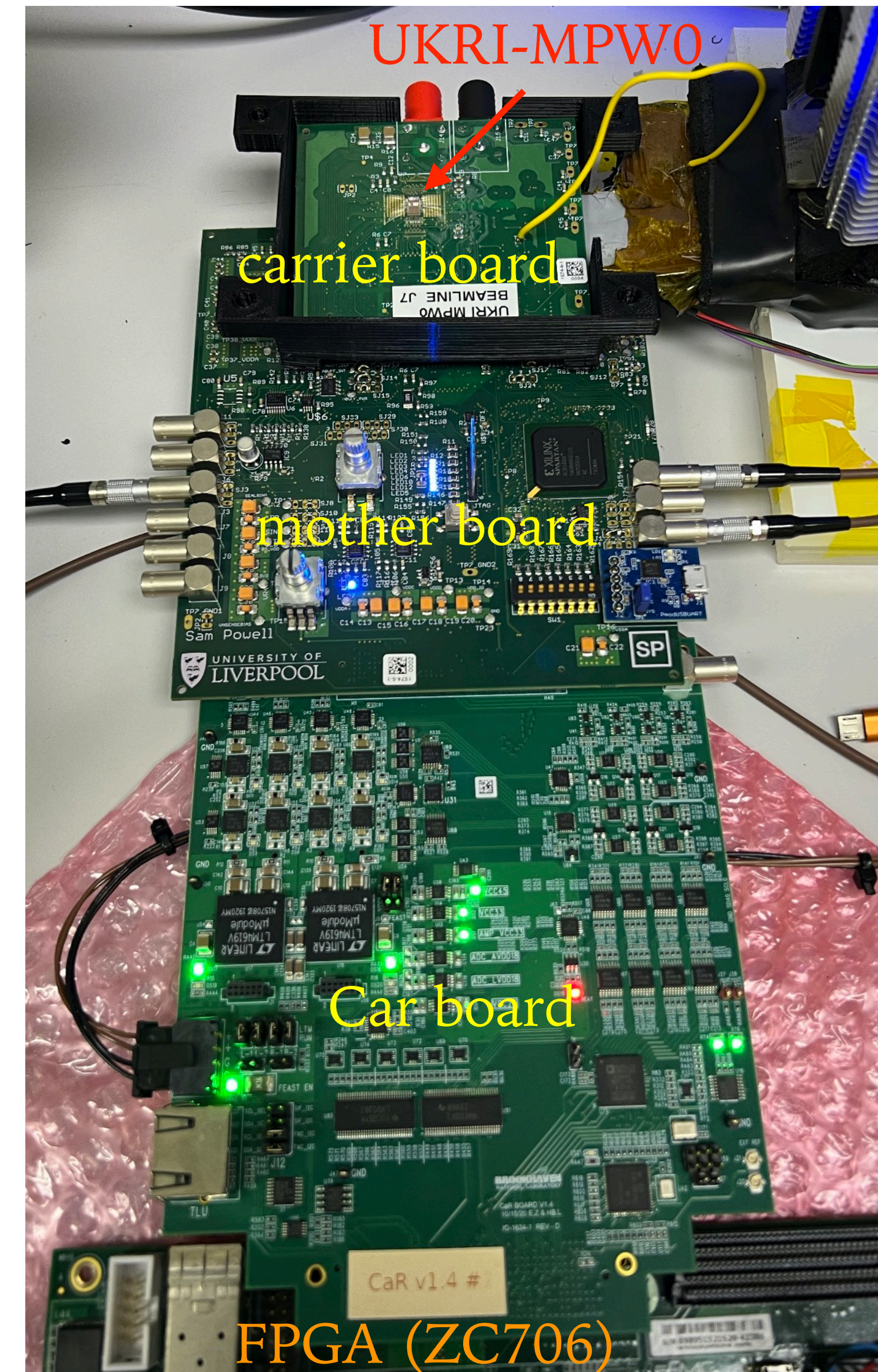
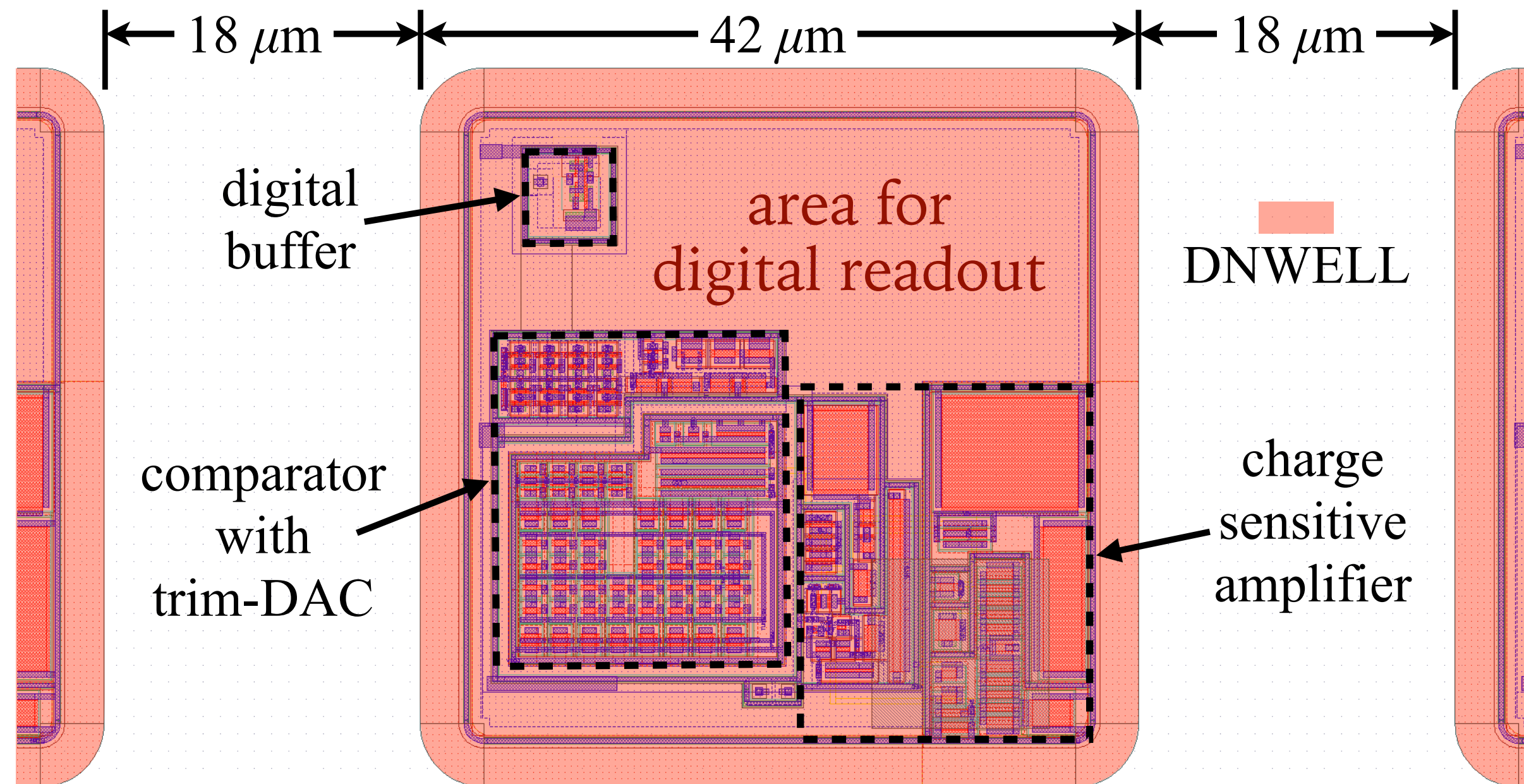
- Pixel matrix has three pixel flavours:
 - Continuous-reset pixel
 - Switched-reset pixel
 - Modulated-reset pixel
- Pixel flavours 1. and 2. have been implemented in a previous HV-CMOS prototype RD50-MPW2 ([C. Zhang TWEPP 2019](#)).
- Pixel flavour 3. modulates the reset speed based on input charge.



Continuous-reset pixel



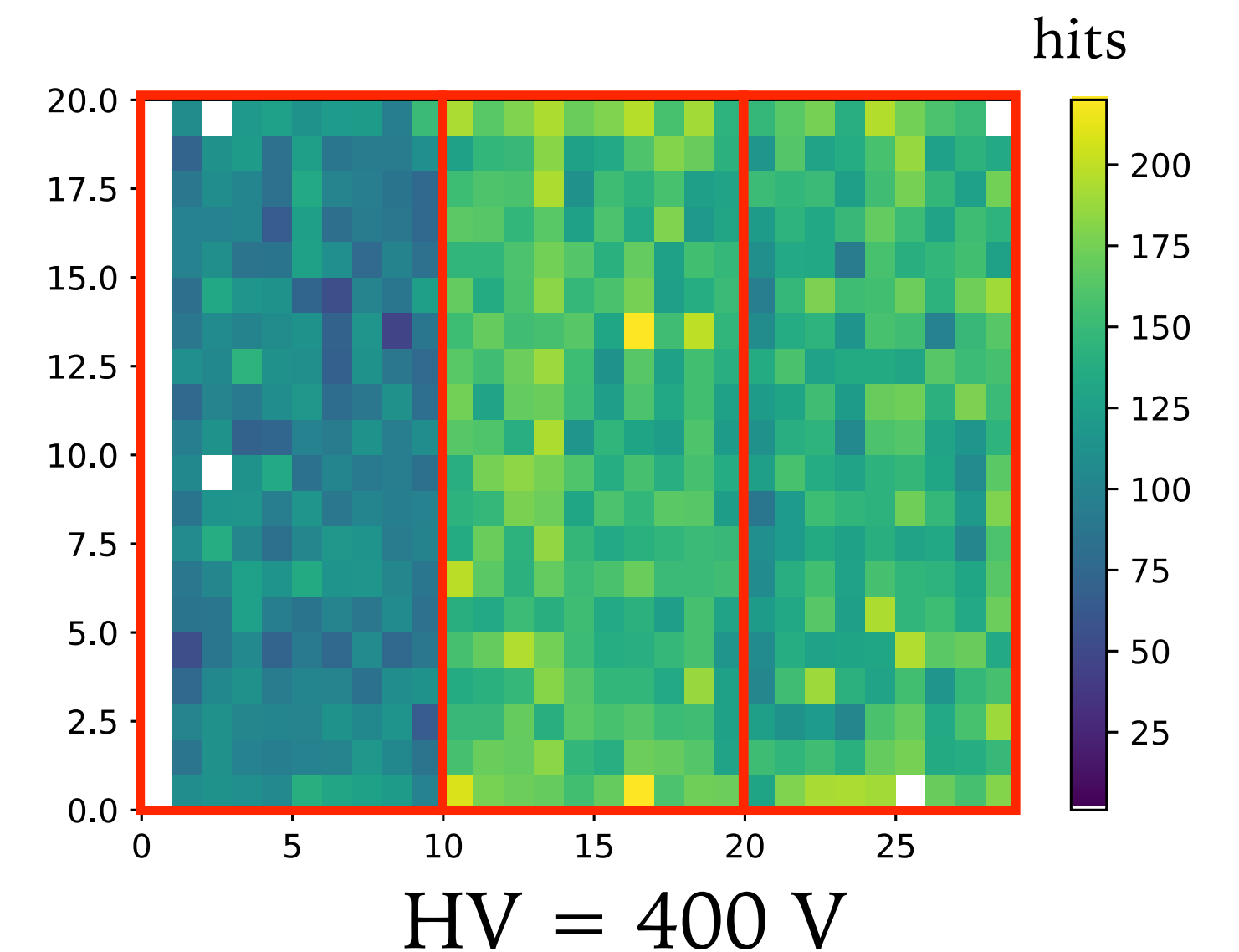
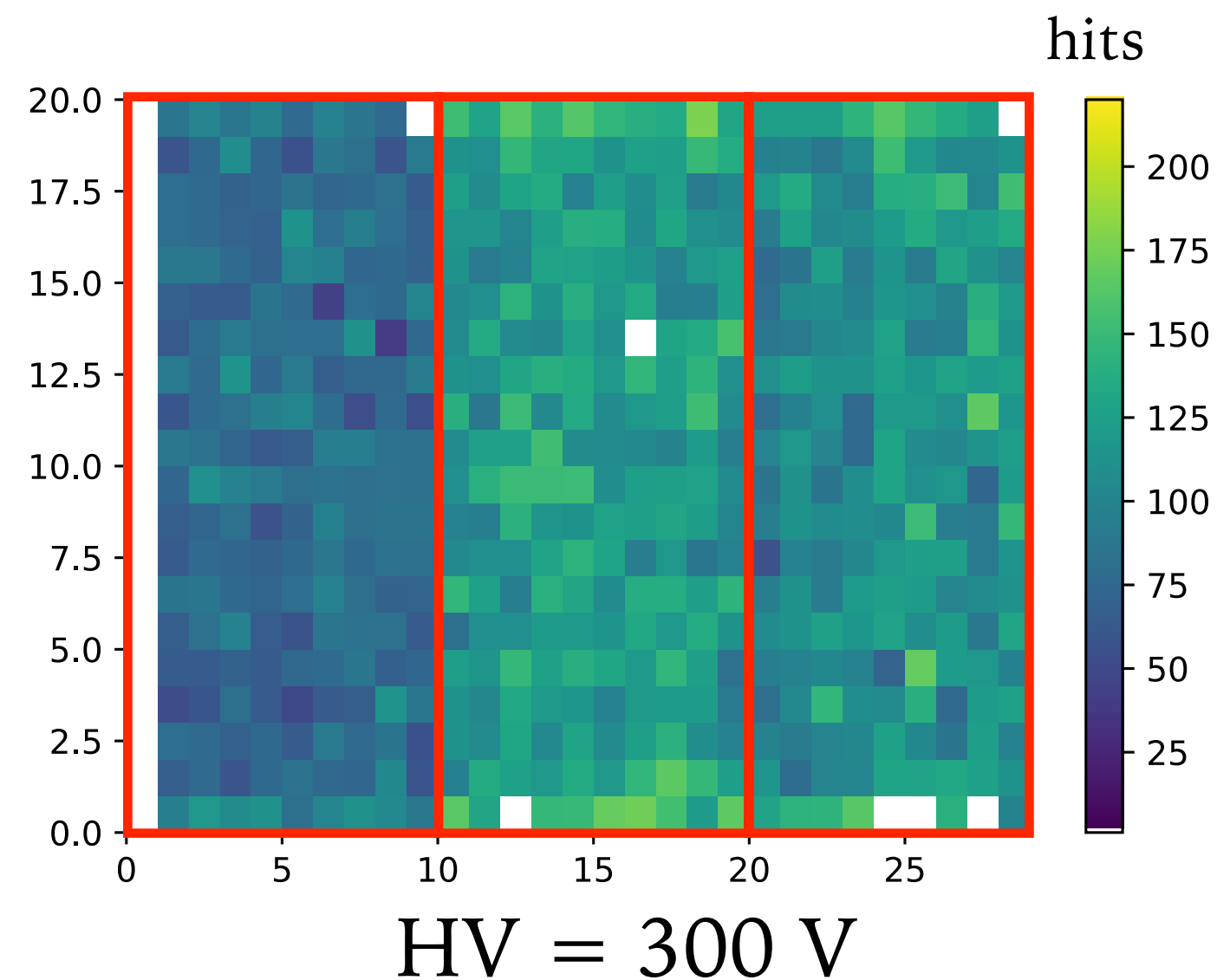
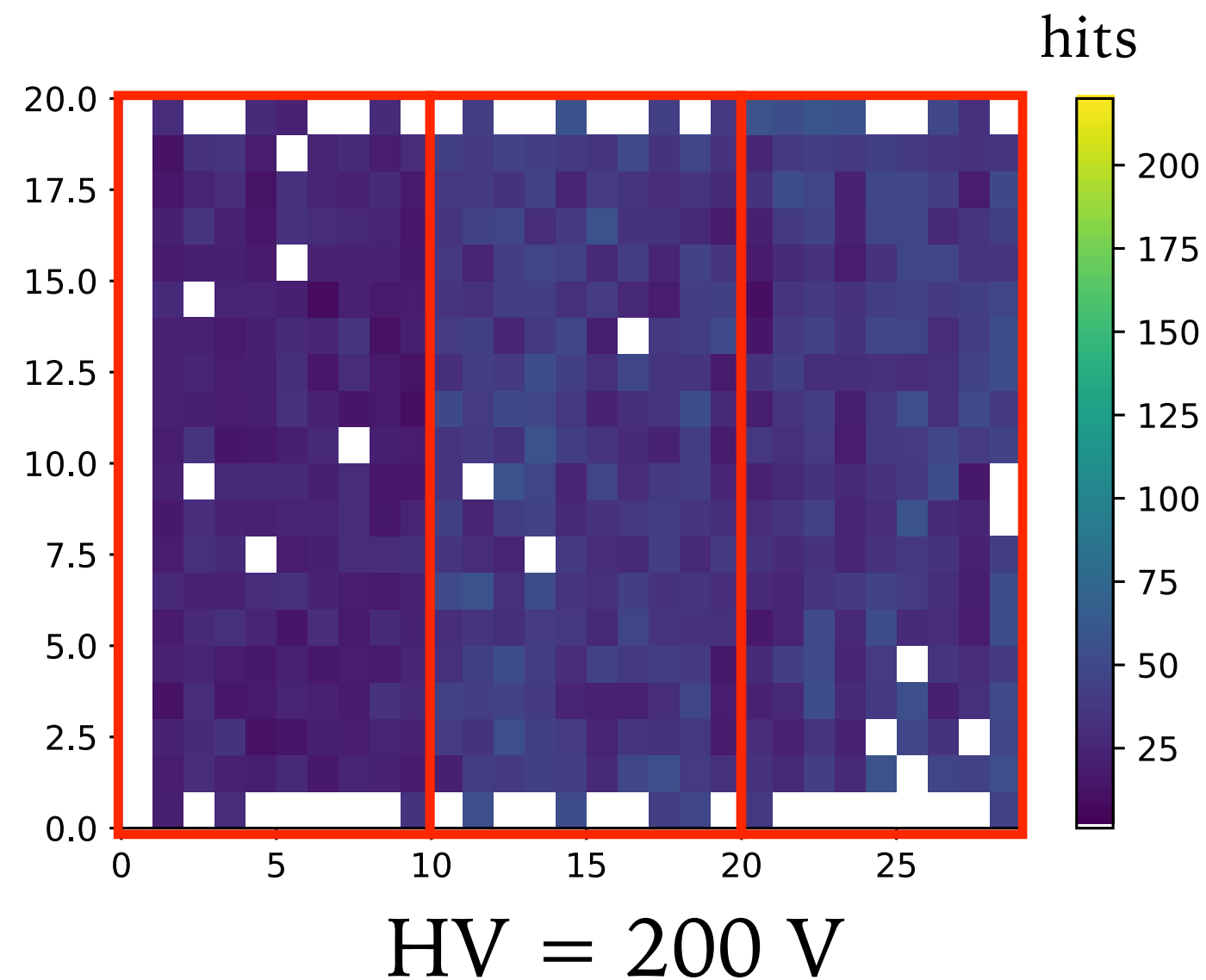
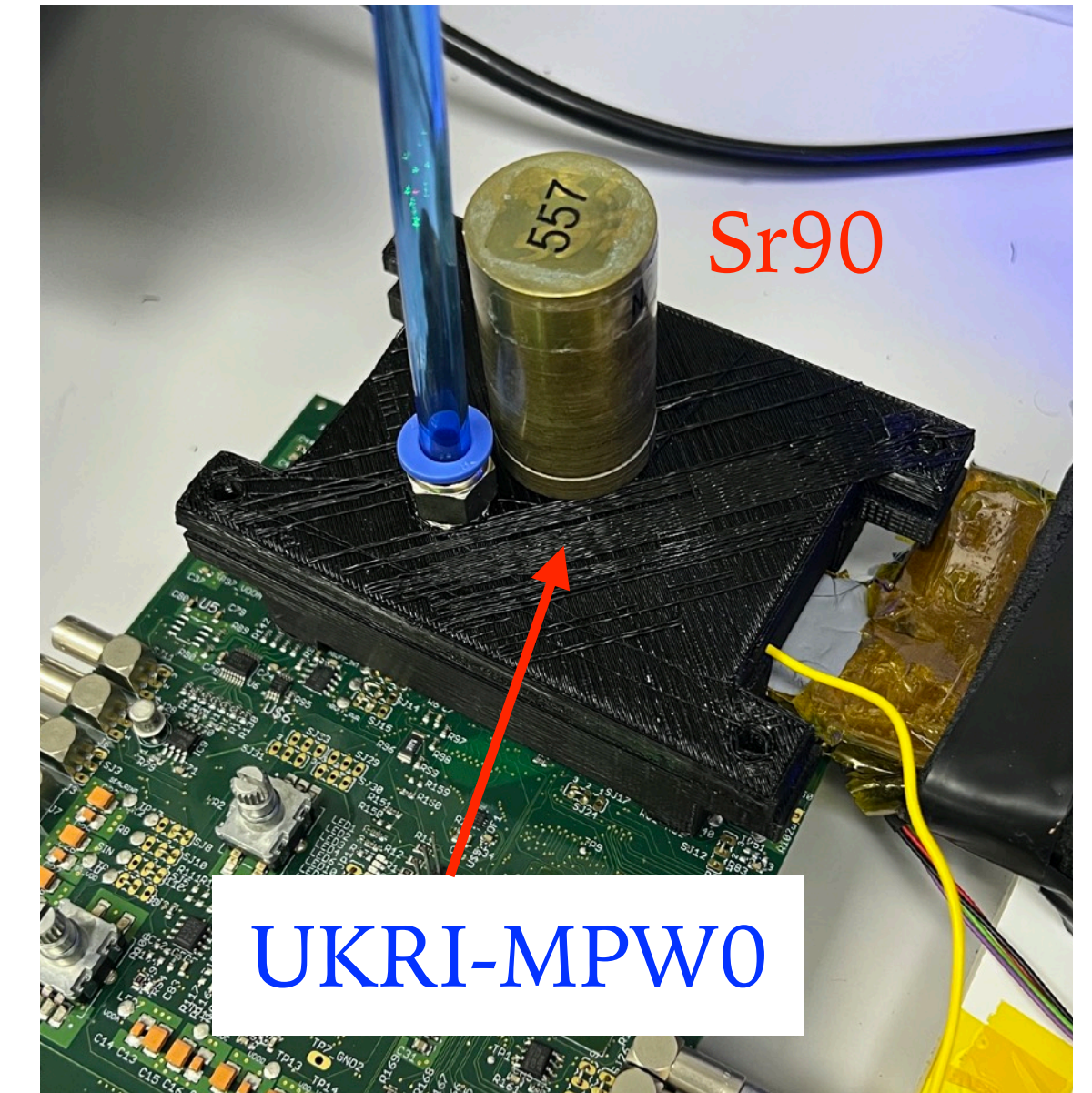
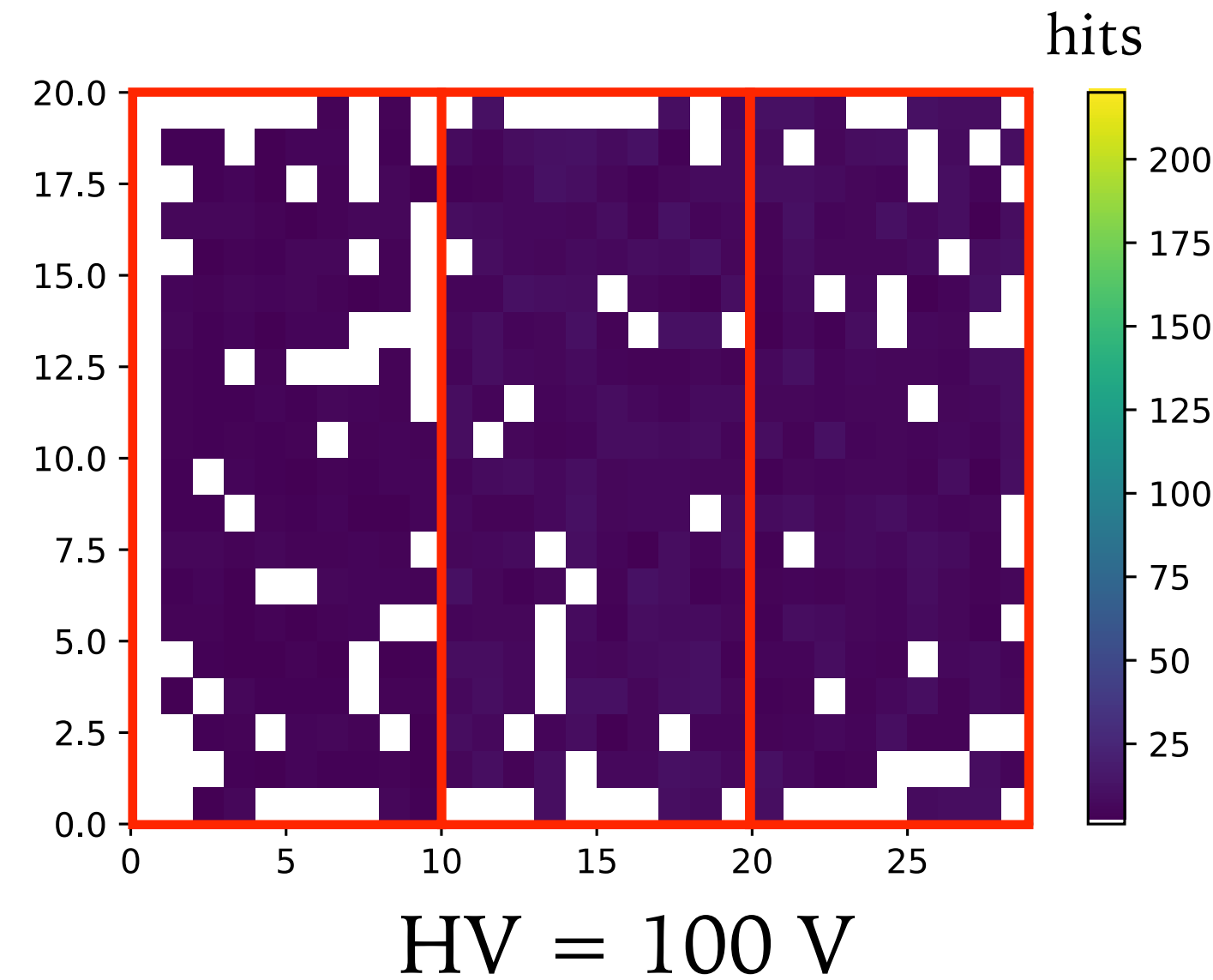
Switched-reset pixel (faster response)



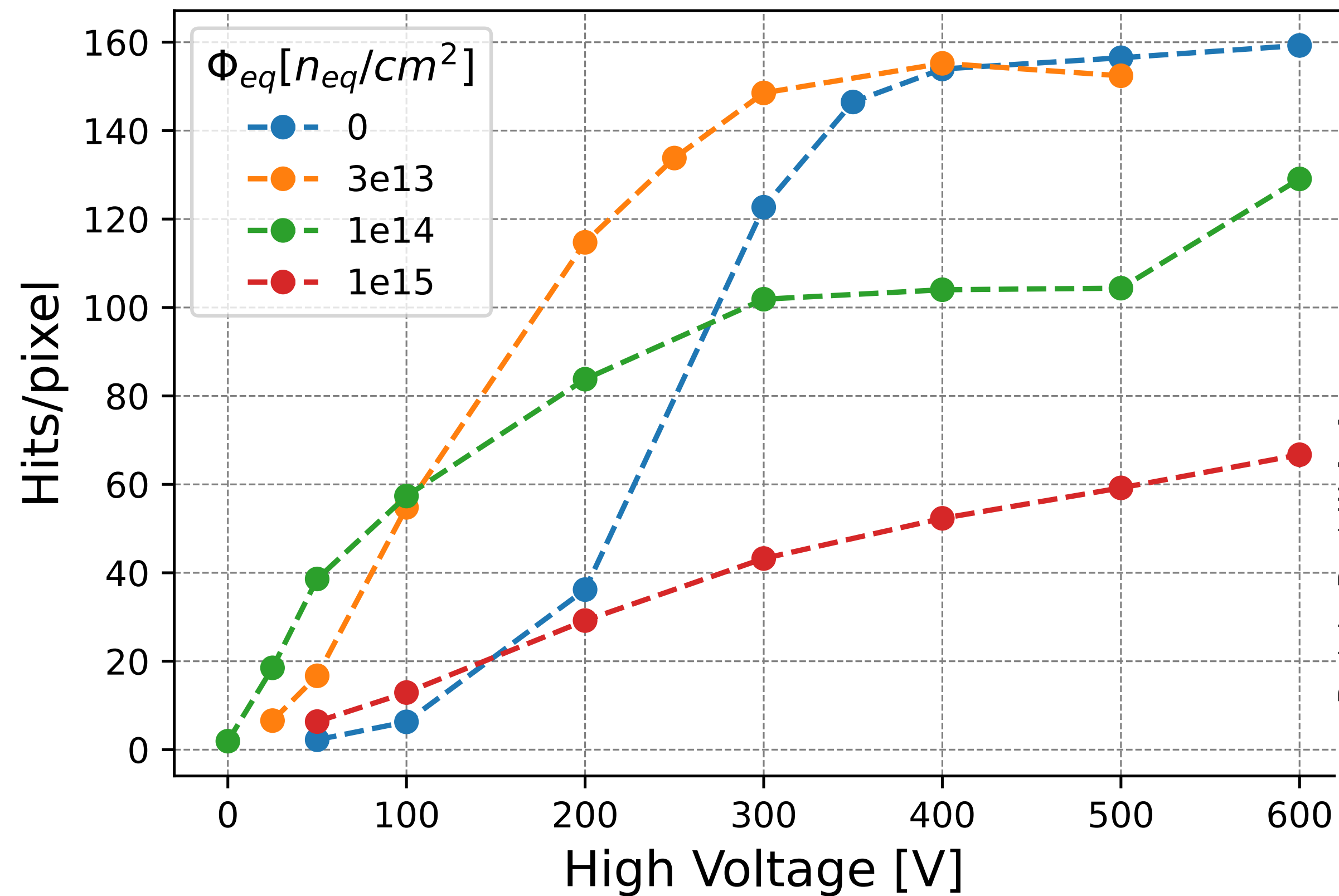
- Pixel comparator output is buffered for readout.
- Each column has own readout pad.
- DAQ is based on **Caribou**.
- Time parameters (ToA, ToT) are digitised off-chip.

Source hit map

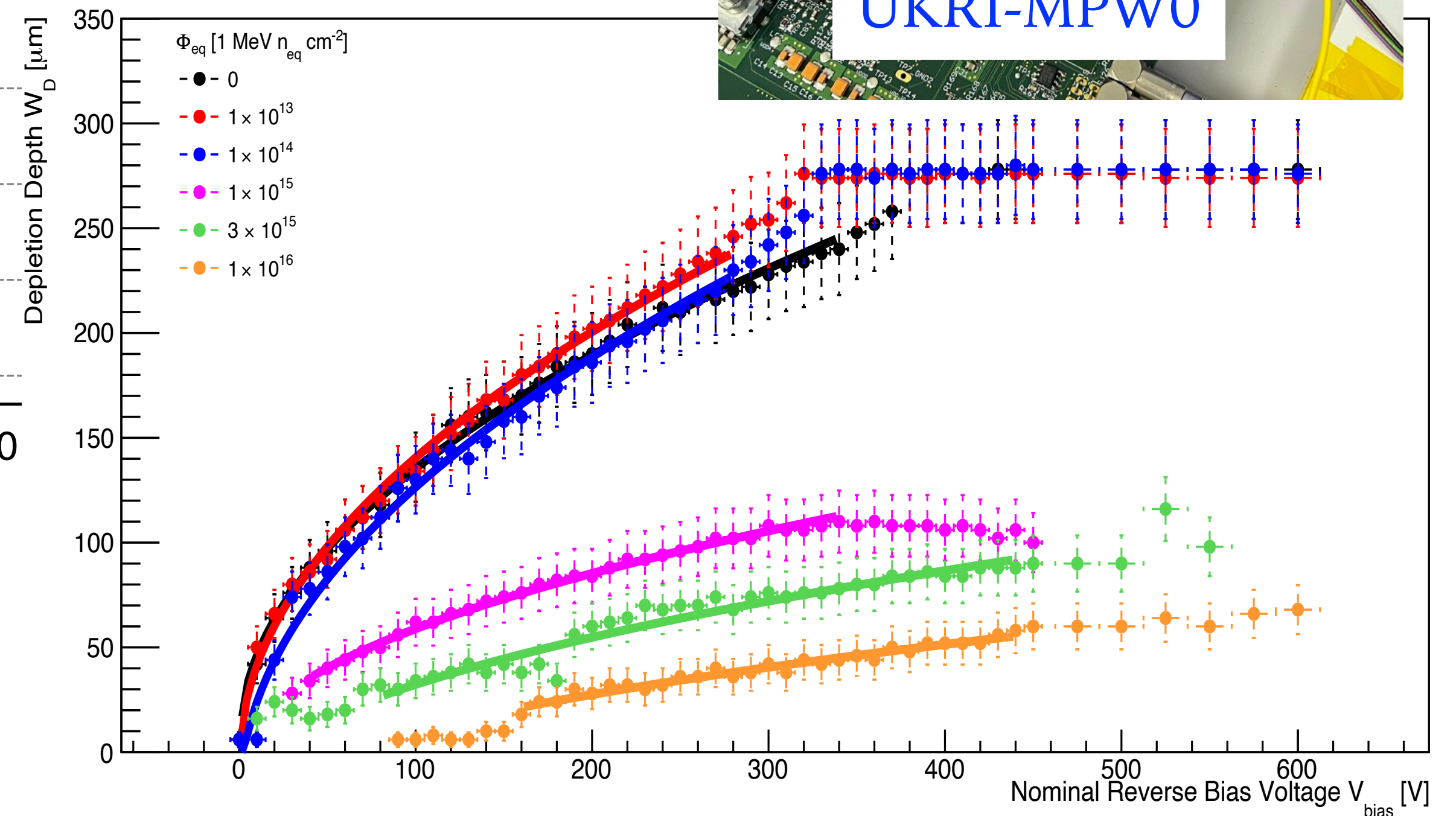
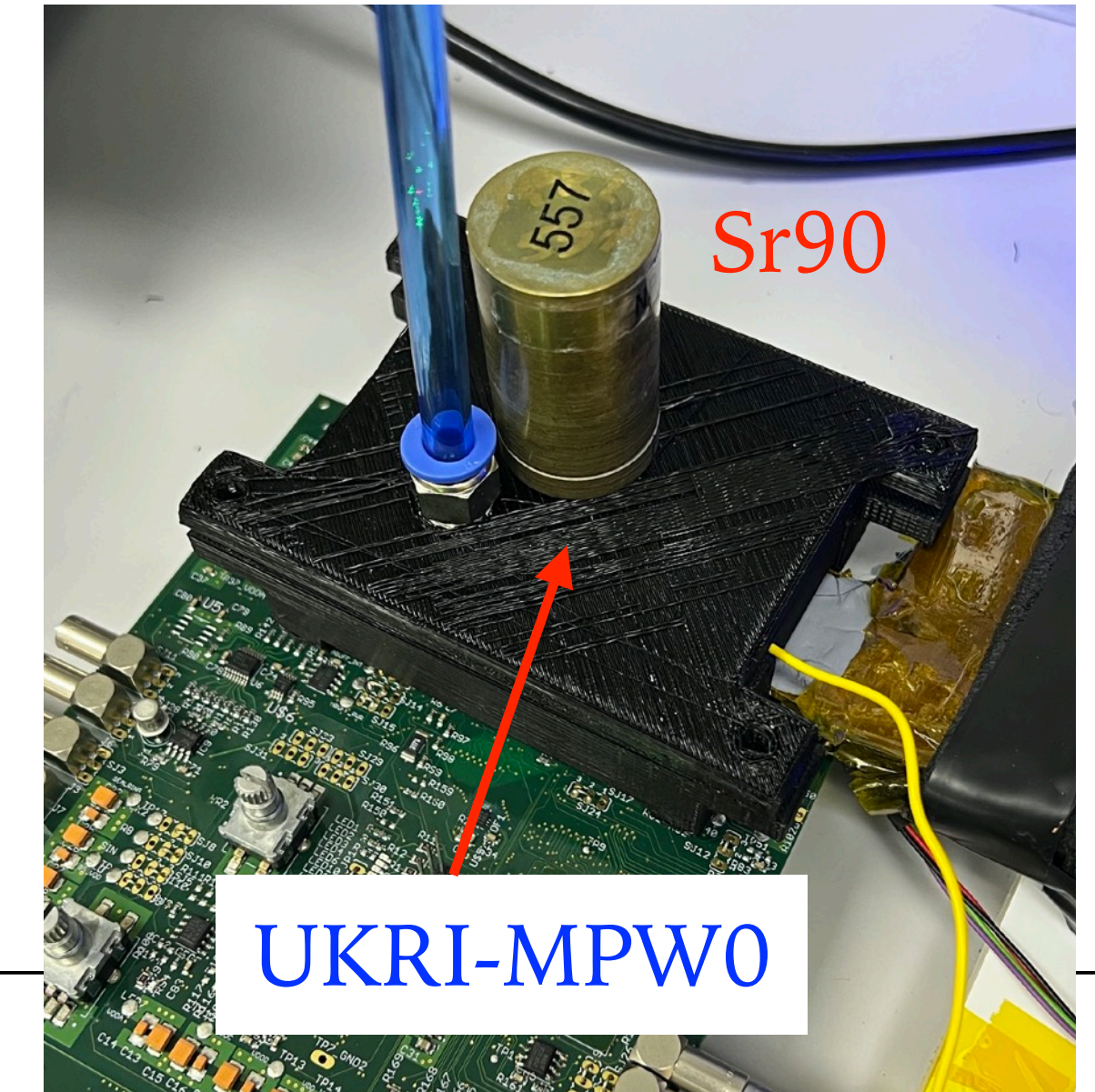
- Used a Sr90 source to plot the number of hits received by pixels over a shutter window of 20 s.
- Hits number increases with High Voltage.
- Pixel flavour in the milder (Switched-reset) detects more hits due to higher gain.



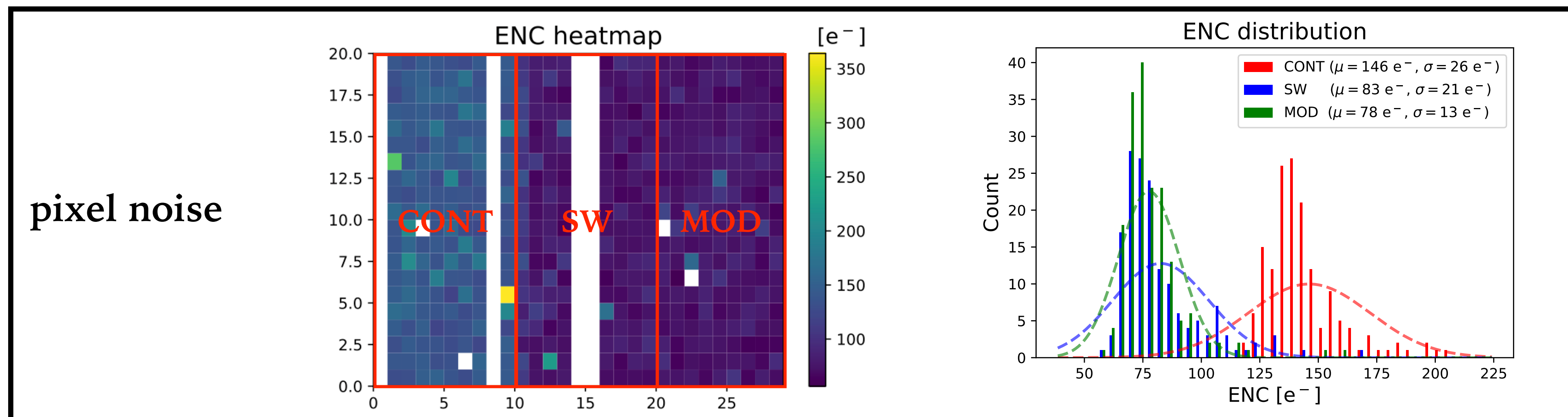
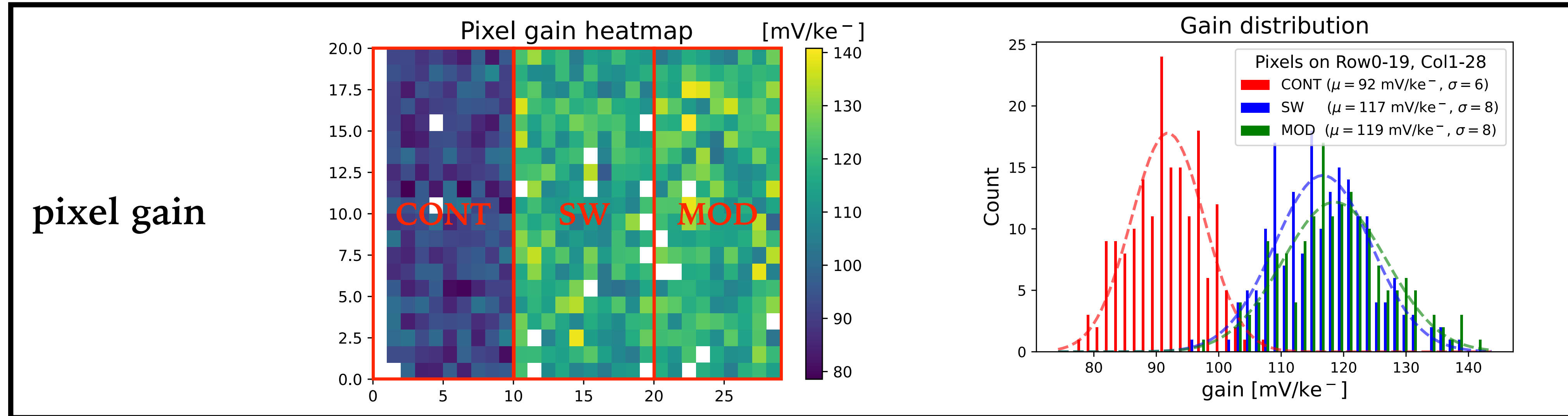
- Plot mean hits per pixel with different High Voltages and for different radiation fluence.



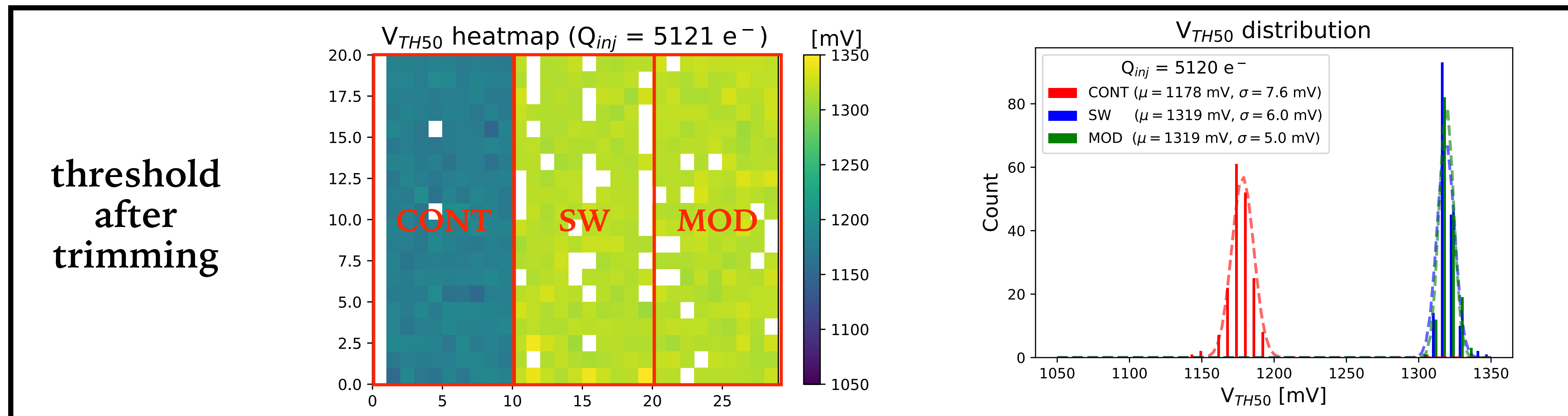
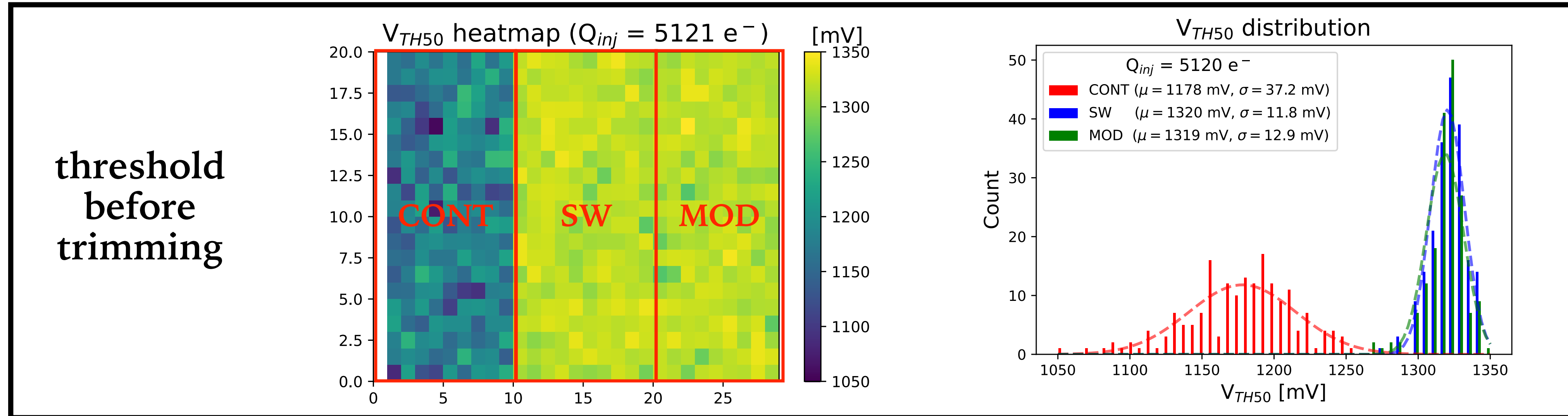
- Agrees with edge-TCT results.



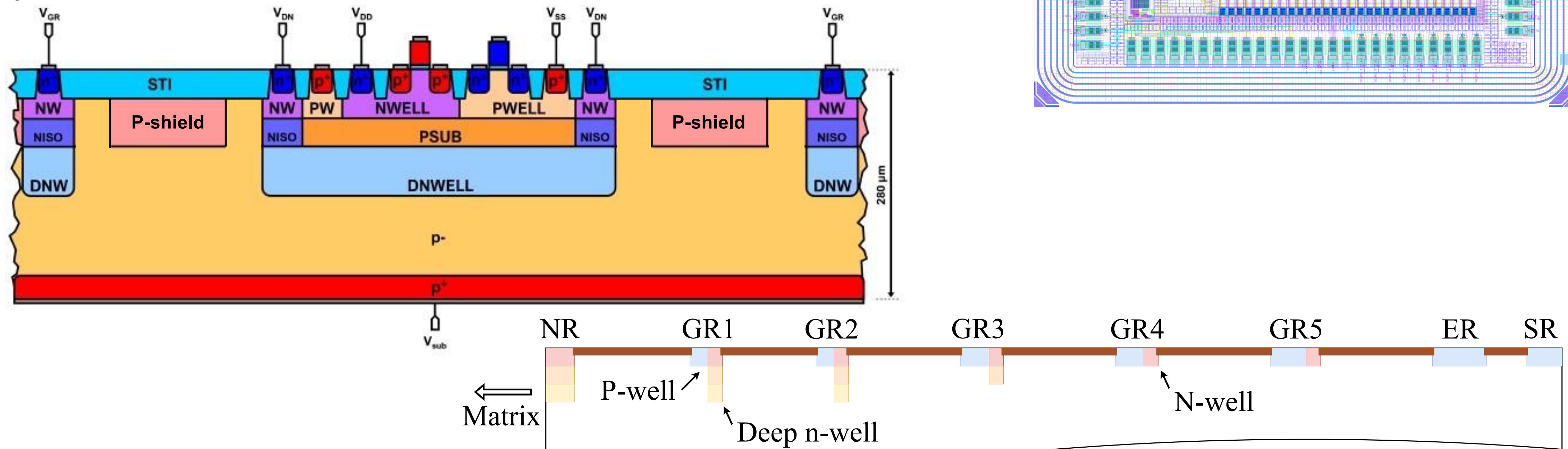
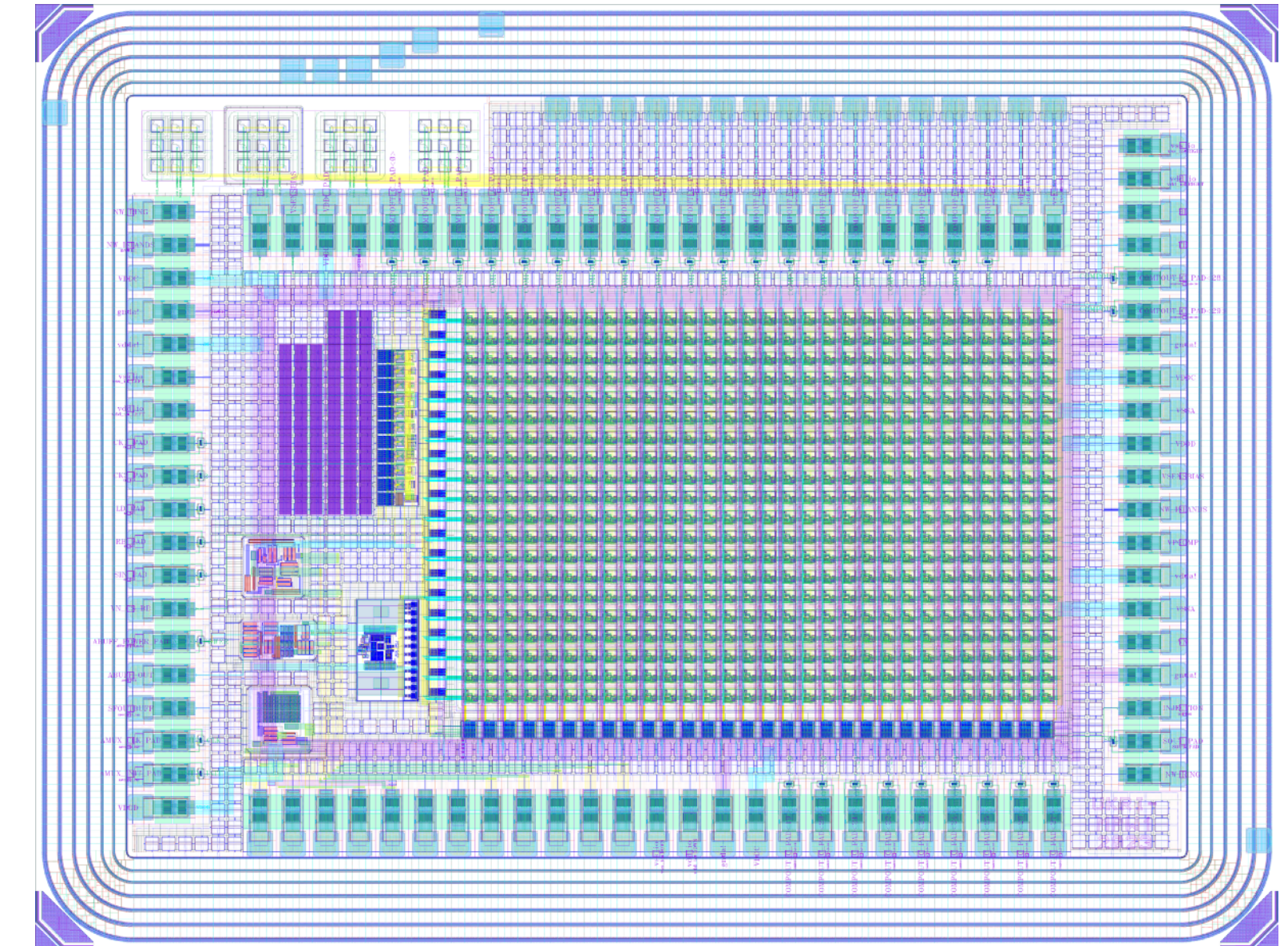
- Pixel performance is measured using S-curve scans.



- Threshold before and after trimming:



- Succeeding UKRI-MPW1 is designed.
- Add a customised low-doped shallow p-type layer (P-shield) beneath STI to prevent parasitic channel.
- Use a new chip ring structure for lower leakage.
 - Guard Rings (GR) have both P-type and N-type wells.
- High voltage can be applied from topside (Seal Ring (SR) and Edge Ring (ER)) or backside.



- Conclusions:

- UKRI-MPW0 is a proof-of-concept HV-CMOS chip with backside-only biasing.
- Breakdown voltage > 600 V.
- After $1e16$ n_{eq}/cm^2 neutron irradiation, depletion depth > 50 μm .
- pixel performance after irradiation has been evaluated.
- In UKRI-MPW1: improve the high leakage current by modifying the chip rings; prevent the channel under STI by adding P-shield.

- Outlook:

- Evaluate UKRI-MPW0 pixel matrix in testbeam.
- UKRI-MPW1 will be delivered in November 2023.